SN74LVC02A-EP QUADRUPLE 2-INPUT POSITIVE-NOR GATE

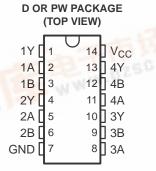
杏海WWW.fi.foWC02A_FP"供应商

SCAS831-MARCH 2007

FEATURES

- Controlled Baseline
 - One Assembly Site
 - One Test Site
 - One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree (1)
- Customer-Specific Configuration Control Can
 Be Supported Along With Major-Change
 Approval
- Inputs Accept Voltages to 5.5 V
- ESD Protection Exceeds JESD 22
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- 2000-V Human-Body Model (A114-A)
- 200-V Machine Model (A115-A)
- 1000-V Charged-Device Model (C101)



DESCRIPTION/ORDERING INFORMATION

The quadruple 2-input positive-NOR gate is designed for 2.7-V to 3.6-V V_{CC} operation.

The SN74LVC02A performs the Boolean function $Y = \overline{A} + \overline{B}$ or $Y = \overline{A} \cdot \overline{B}$ in positive logic.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

ORDERING INFORMATION(1)

T _A	PACE	(AGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	TSSOP - PW	Tape and reel	SN74LVC02AMPWREP	LVC02AM

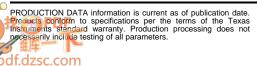
- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.
- (2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (EACH GATE)

INPU	JTS	OUTPUT
Α	В	19 Y
Н.	Х	1///JL
X	M.H	L
LSE.	L	Н



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LOGIC DIAGRAM, EACH GATE (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			N	IIN	MAX	UNIT
V _{CC}	Supply voltage range		_	0.5	6.5	V
VI	Input voltage range (2)		_	0.5	6.5	V
Vo	Output voltage range ⁽²⁾⁽³⁾		_	0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V ₁ < 0			-50	mA
I _{OK}	Output clamp current	V _O < 0			-50	mA
Io	Continuous output current				±50	mA
	Continuous current through V _{CC} or GND				±100	mA
0	Dealers thereal in a dealer (4)	D package			86	0000
θ_{JA}	Package thermal impedance ⁽⁴⁾	PW package			113	°C/W
T _{stg}	Storage temperature range		-	-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V	Cupply voltage	Operating	2	3.6	V
V _{CC}	Supply voltage	Data retention only	1.5		v
V_{IH}	High-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		٧
V_{IL}	Low-level input voltage	V _{CC} = 2.7 V to 3.6 V		0.8	V
V_{I}	Input voltage		0	5.5	V
Vo	Output voltage		0	V_{CC}	٧
	High level output output	V _{CC} = 2.7 V		-12	mA
I _{OH}	High-level output current	$V_{CC} = 3 V$		-24	IIIA
	Low lovel output ourrent	V _{CC} = 2.7 V		12	mA
I _{OL}	Low-level output current	V _{CC} = 3 V		24	IIIA
T_A	Operating free-air temperature		-55	125	°C

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

 ⁽³⁾ The value of V_{CC} is provided in the recommended operating conditions table.
 (4) The package thermal impedance is calculated in accordance with JESD 51-7.

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Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾ MAX	UNIT
	$I_{OH} = -100 \mu\text{A}$	2.7 V to 3.6 V	$V_{CC} - 0.2$		
V	10 mA	2.7 V	2.2		V
V _{OH}	$I_{OH} = -12 \text{ mA}$	3 V	2.4		V
	I _{OH} = -24 mA	3 V	2.2		
	$I_{OL} = 100 \mu A$	2.7 V to 3.6 V		0.2	
V_{OL}	I _{OL} = 12 mA	2.7 V		0.4	V
	I _{OL} = 24 mA	3 V		0.55	
I _I	V _I = 5.5 V or GND	3.6 V		±5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		10	μА
ΔI_{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V		500	μА
C _i	$V_I = V_{CC}$ or GND	3.3 V		5	pF

⁽¹⁾ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT) A or B	TO (OUTPUT)	V _{CC} = 2.7 V	V _{CC} = 3.3 V ± 0.3 V		UNIT	
	(INFOT)	(001F01)	MIN MAX	MIN	MAX		
t _{pd}	A or B	Υ	6.5	1	5.5	ns	

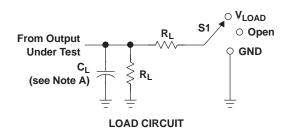
Operating Characteristics

 $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{CC} = 2.5 V	$V_{CC} = 3.3 \text{ V}$	UNIT
	TAKAMETEK	TEST CONDITIONS	TYP	TYP	ONIT
C_{pd}	Power dissipation capacitance per gate	f = 10 MHz	8.5	9.5	pF

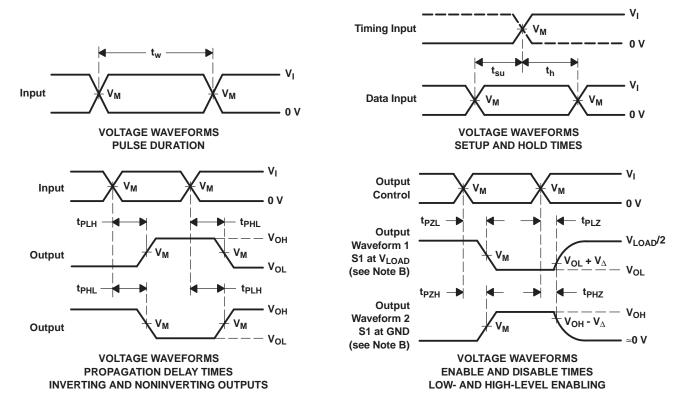


PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

.,	INF	PUTS	.,	W	0	_	.,
V _{CC}	VI	t _r /t _f	V _M	V_{LOAD}	CL	R_L	$oldsymbol{V}_{\Delta}$
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω .
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



PACKA

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Pea
SN74LVC02AMPWREP	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
V62/06660-01XE	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new **PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retard in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LVC02A-EP:

Catalog: SN74LVC02A

Automotive: SN74LVC02A-Q1



PACKA

NOTE: Qualified Version Definitions:

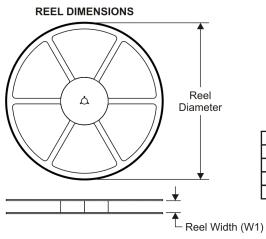
- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects



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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

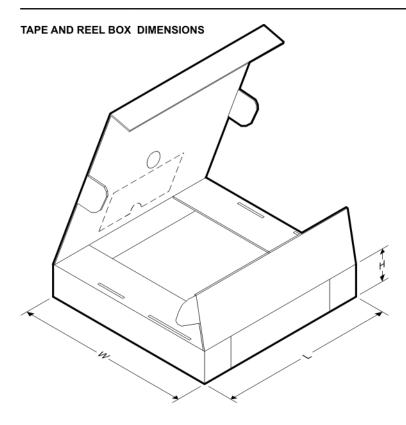
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC02AMPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1





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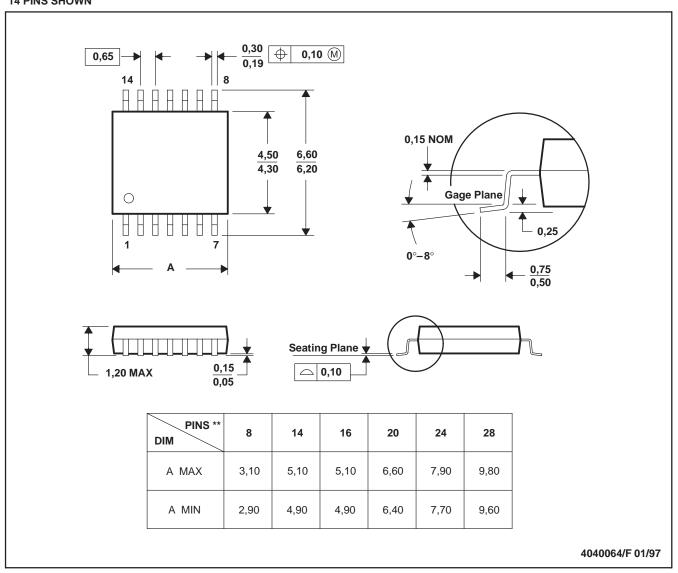
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC02AMPWREP	TSSOP	PW	14	2000	346.0	346.0	29.0

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

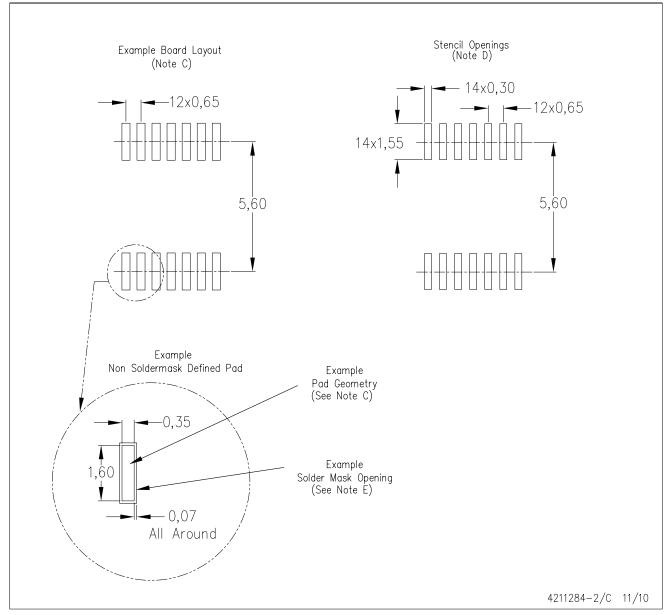
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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